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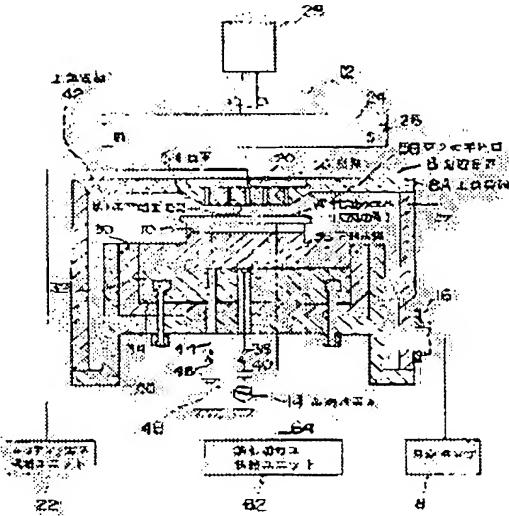
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(54) PLASMA PROCESSING EQUIPMENT

(57)Abstract:

PURPOSE: To uniformize a processing shape of an object body in a plasma processing equipment that executes plasma processing of the object body put on either one of two electrodes installed in parallel and in opposite to each other by forming the electrode opposite to the object body to have a projecting shape in the direction toward the object body.

CONSTITUTION: A plasma processing equipment 14 of this invention applies high frequency wave between the upper and lower electrodes 42 and 36 to generate plasma for executing plasma processing on a wafer W. In this case, active species such as molecules and ions activated during discharging plasma acts on the surface of the wafer W. Here, since there is a section 50 formed to be projected toward the wafer W on the lower surface of the upper electrode 42, the active species, etc., go over to the whole area of the surface of the wafer and nearly uniformly act on the whole area. With this, a processing shape of the wafer such as contact holes formed by etching can be evenly uniformized over the entire surface of the wafer.



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